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# Laser dressing of tools

SSOM Engelberg Lectures on Optics

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# Grinding

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## stock removal grinding

- rough grinding
- high ablation rates
- rough surface



## precision grinding

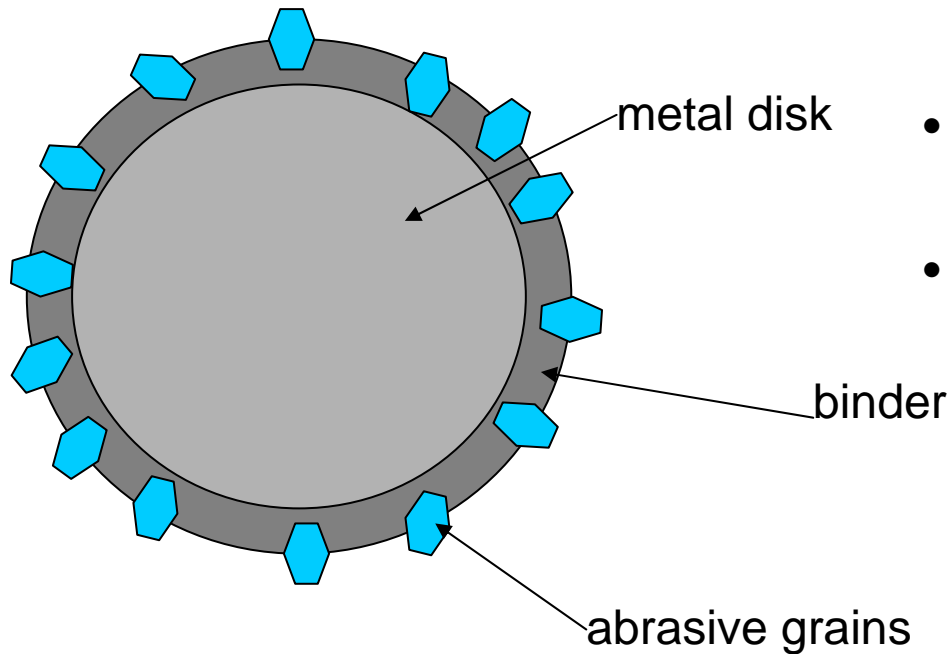
- finish grinding
- smooth surface
- high quality
- low tolerances



# Schematic of grinding wheel

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## grinding wheel



## goals

- long wear time
- high ablation rate
- high precision

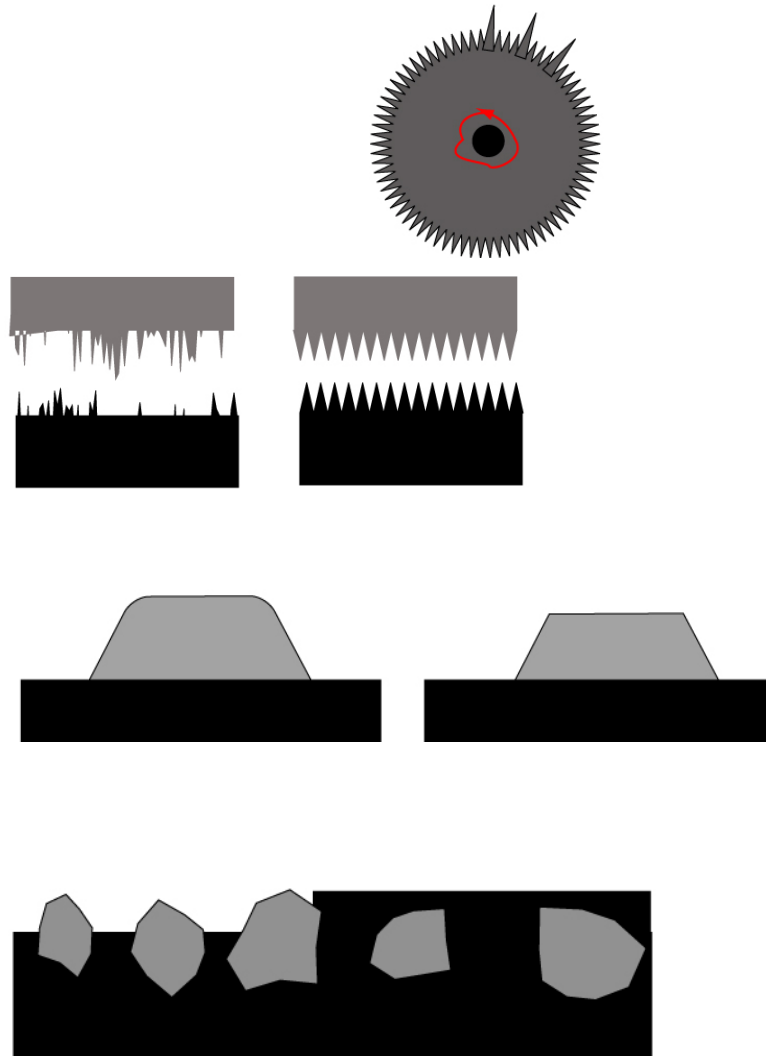
## important parameters

- grain material  
 $\text{Al}_2\text{O}_3$ , cBN, SiC, diamond
- binder  
resin, metal, vitrified, organic
- grain density
- surface roughness
- grain size

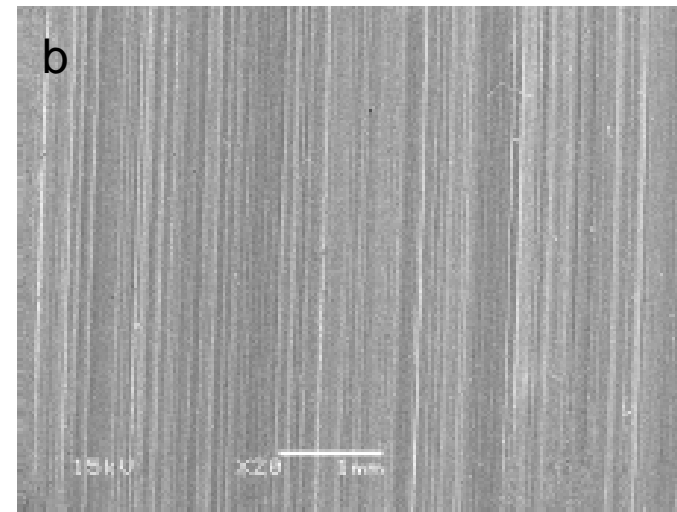
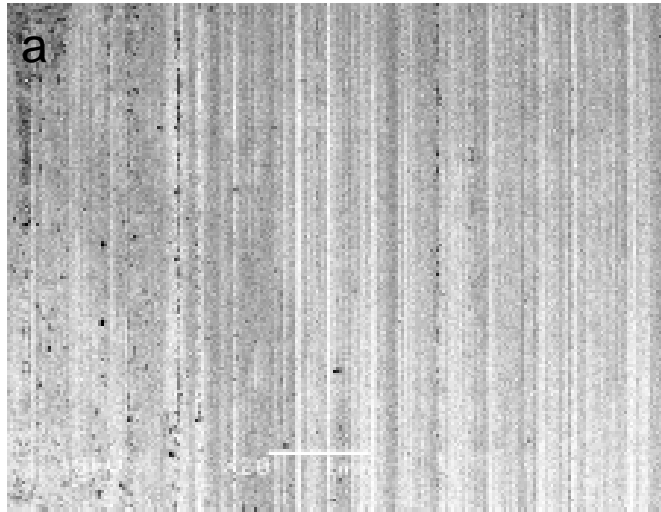
# Why dressing?

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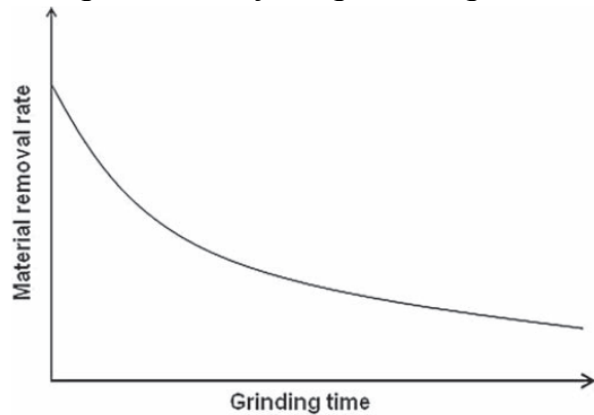
- reduction of vibration
- improved surface finish
- re-sharpen cutting edges
- exposing fresh grains



# Wearing out of grinding tools



Surface situation after grinding: a) undressed grinding wheel, b) dressed grinding wheel  
Wang et al.: Key Engineering Materials 329, 2007



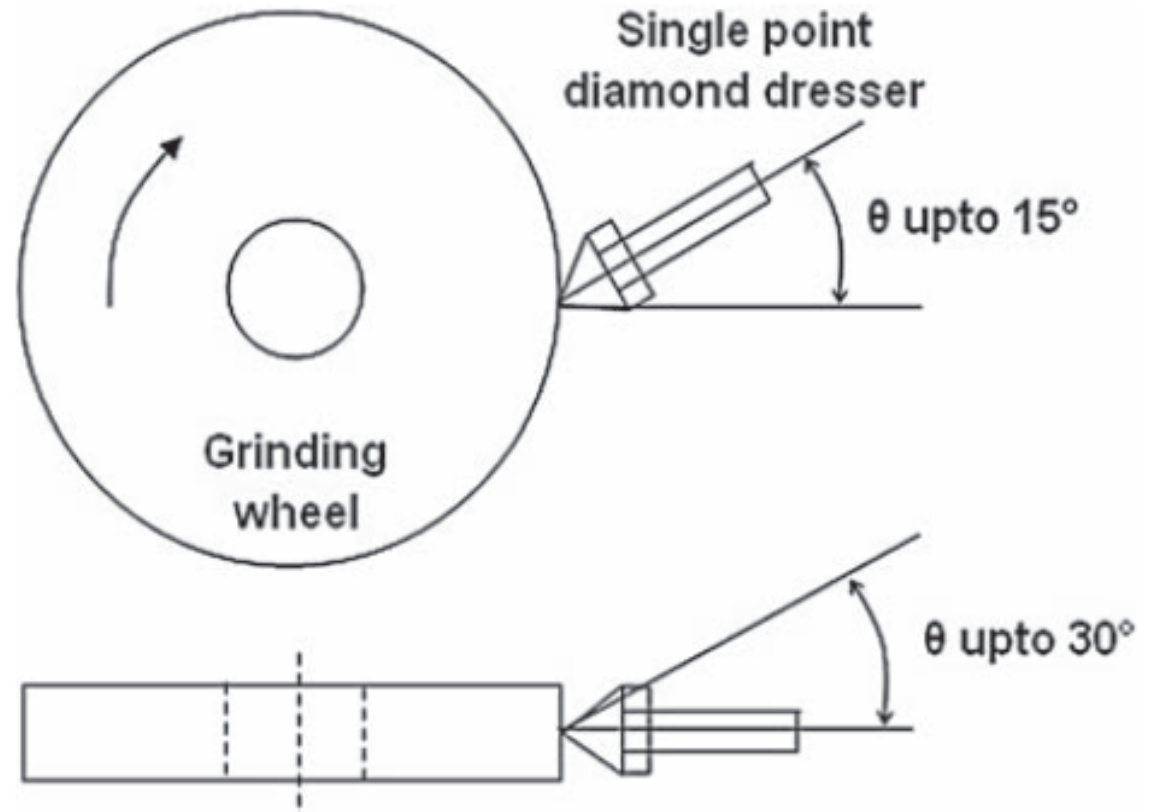
- blunting of cutting edges
- cracking of abrasive grains
- debonding of grains

decrease of material removal efficiency due to outwearing of the abrasive tool

# Conventional dressing

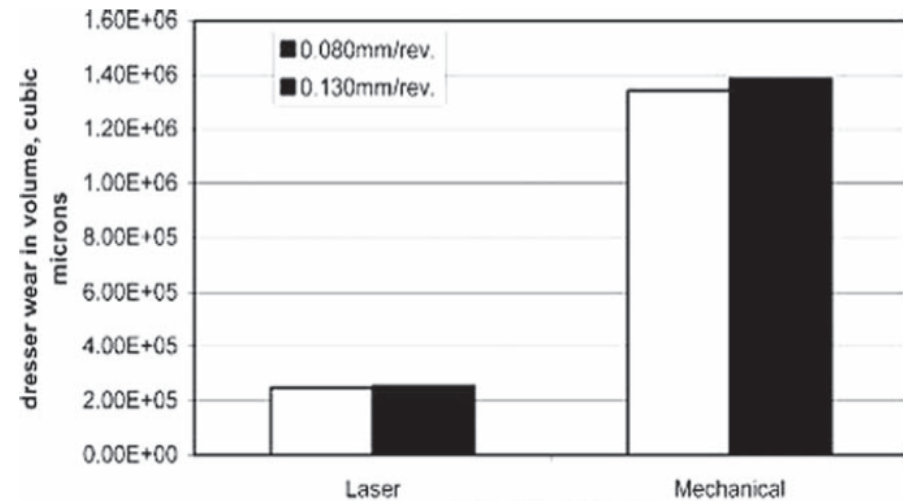
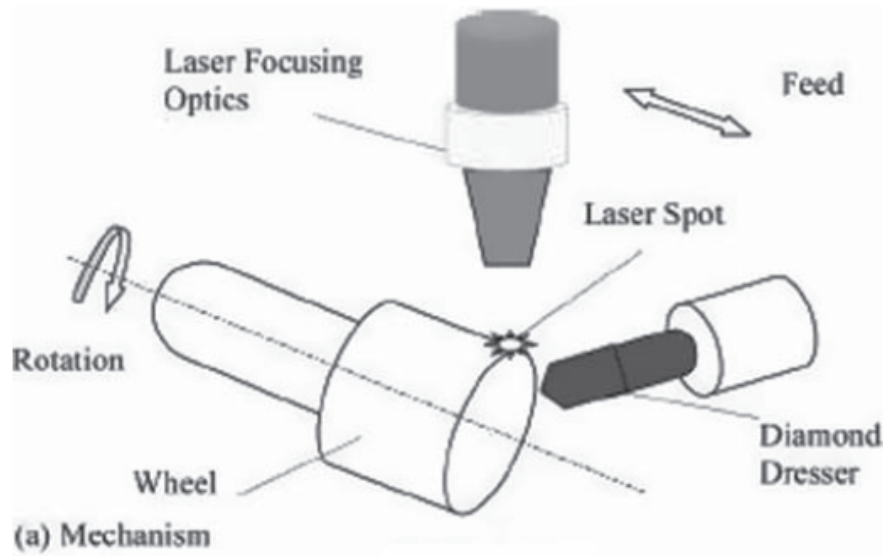
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- mechanical dressing
- dressing tool (diamond)
- surface of dressing tool
- time consuming (hard materials)
- inefficient: 10% material removal with grinding, 90% with dressing



Laser Fabrication and Machining of Materials, *Springer US*, 2008

# Laser assisted dressing

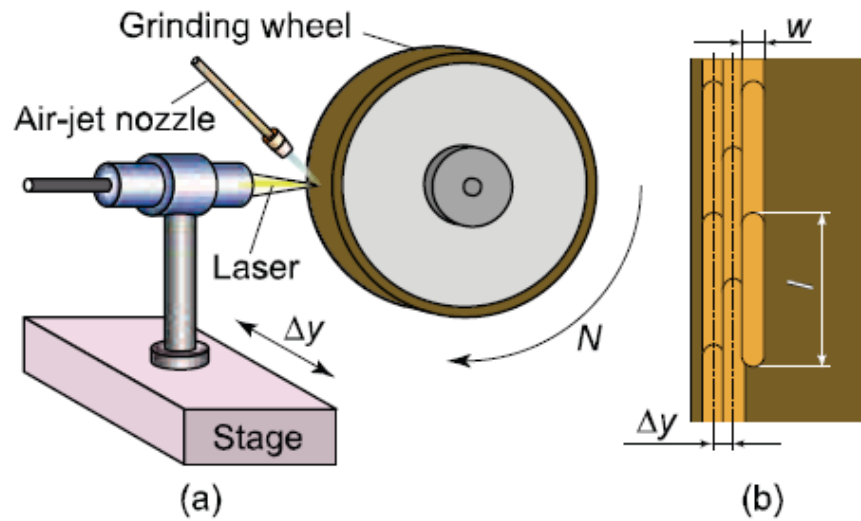


Zhang, Shin: *Int. Journal of Machine Tools and Manufacture*, 42, 2002

- pre-heating of work piece
- softening of material
- easier removal with dressing tool
- weaker forces on dressing tool, increasing life time
- improvement of surface quality

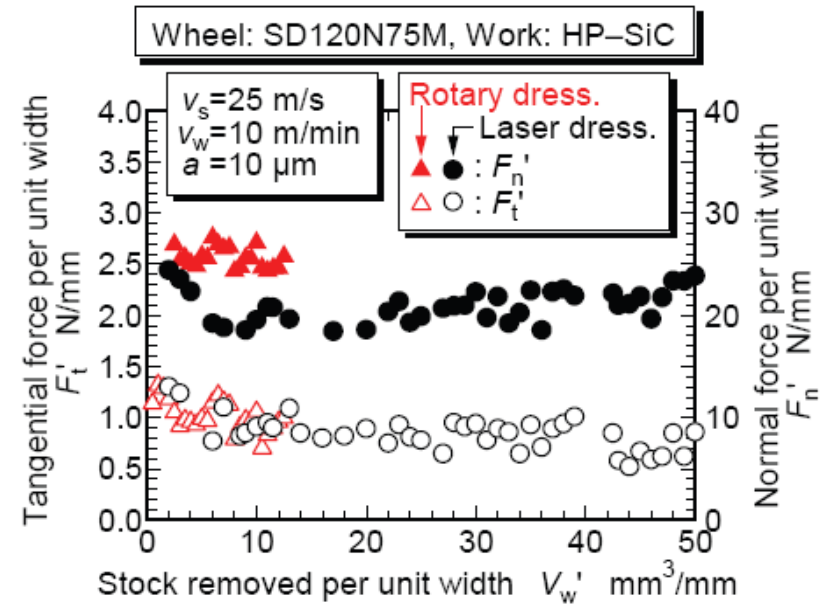
# Laser dressing of SiC or diamond grinding wheels

Ablation of the grinding wheel by melting and blow out with ms pulses (Nd:YAG laser, up to 1 kW)



a) exp. setup, b) overlapping of thermal traces on grinding wheel surface

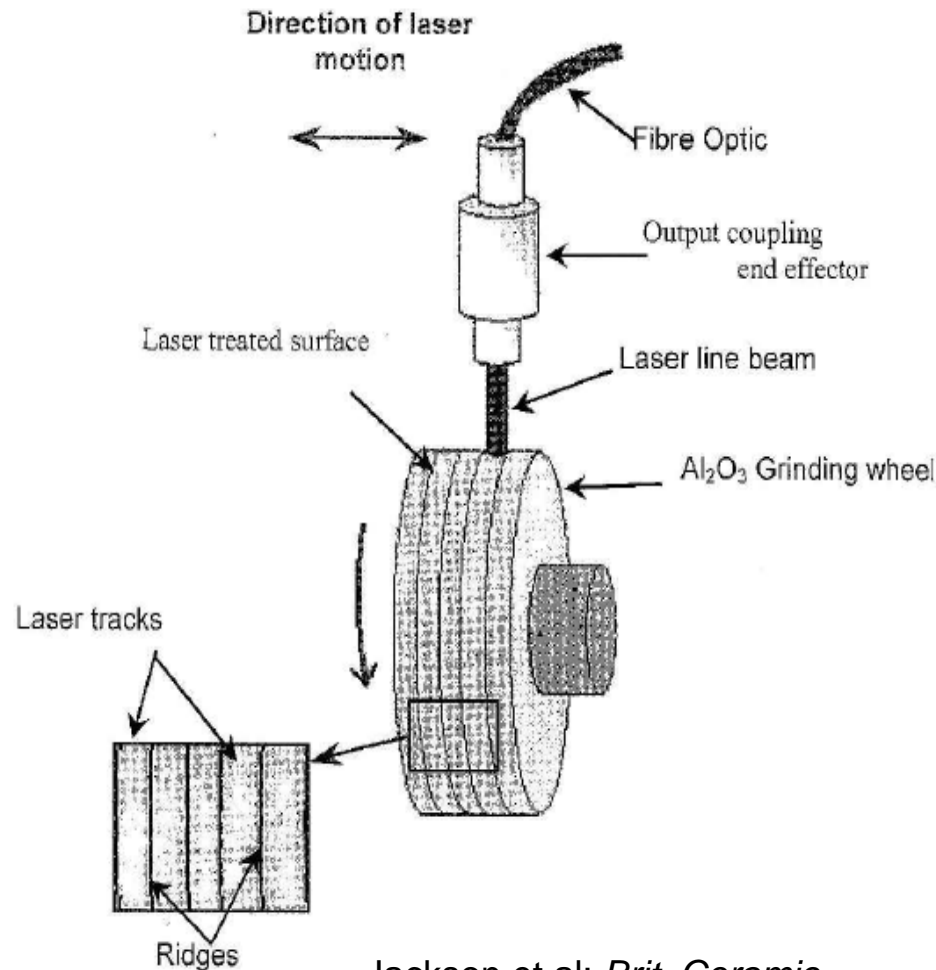
Hosokawa et al: *Annals of the CIRP* 55, 2006



forces during grinding process



# Dressing of Al<sub>2</sub>O<sub>3</sub> grinding wheels



Jackson et al: *Brit. Ceramic Trans.* 102, 2003

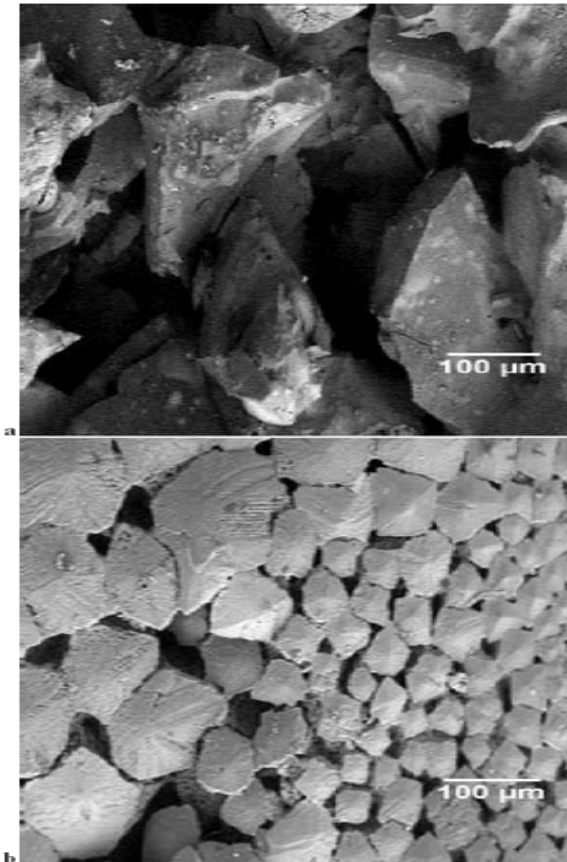
laser  
type: Nd:YAG  
op. mode: cw  
power: 2.5 kW  
speed: 50 cm/s

- no air nozzle
- cw for high heat influence
- little material removal
- goal: restructure the wheel surface

# Rapid solidification

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- cracking and melting of grains
- fast re-crystallization of the surface
- smoother surface
- bonding between grinding grains
- change of grain shapes

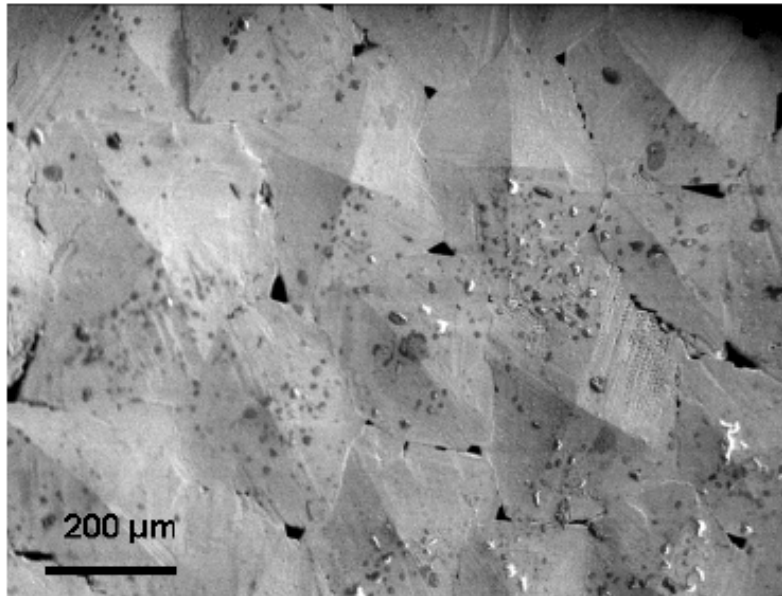


$Al_2O_3$  Grinding wheel:

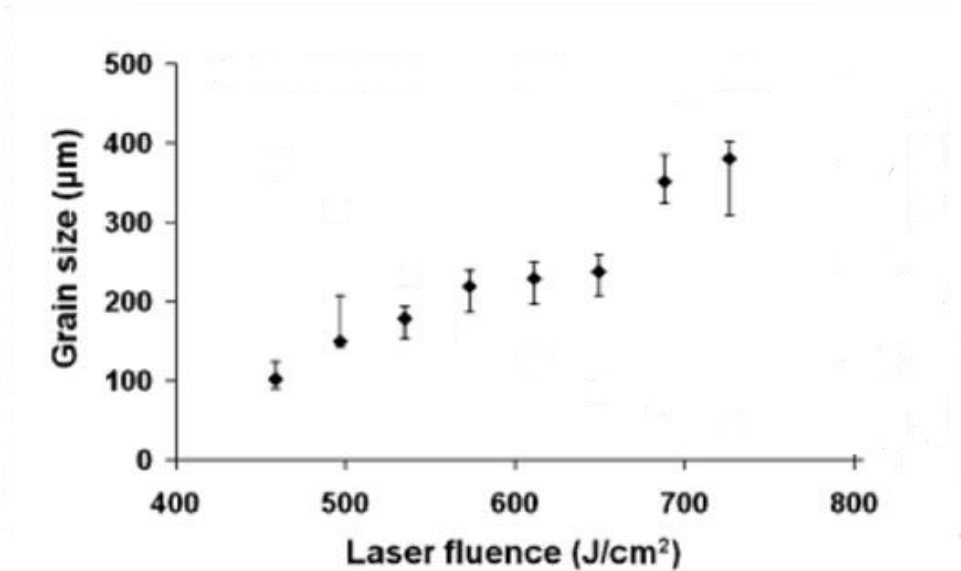
top before laser dressing,  
bottom: after laser dressing

Jackson et al: *Brit. Ceramic Trans.* 102, 2003

# Reforming of cutting edges and microstructures



Harimkar, et al. :*J. Phys. D: Appl. Phys.*39, 2006

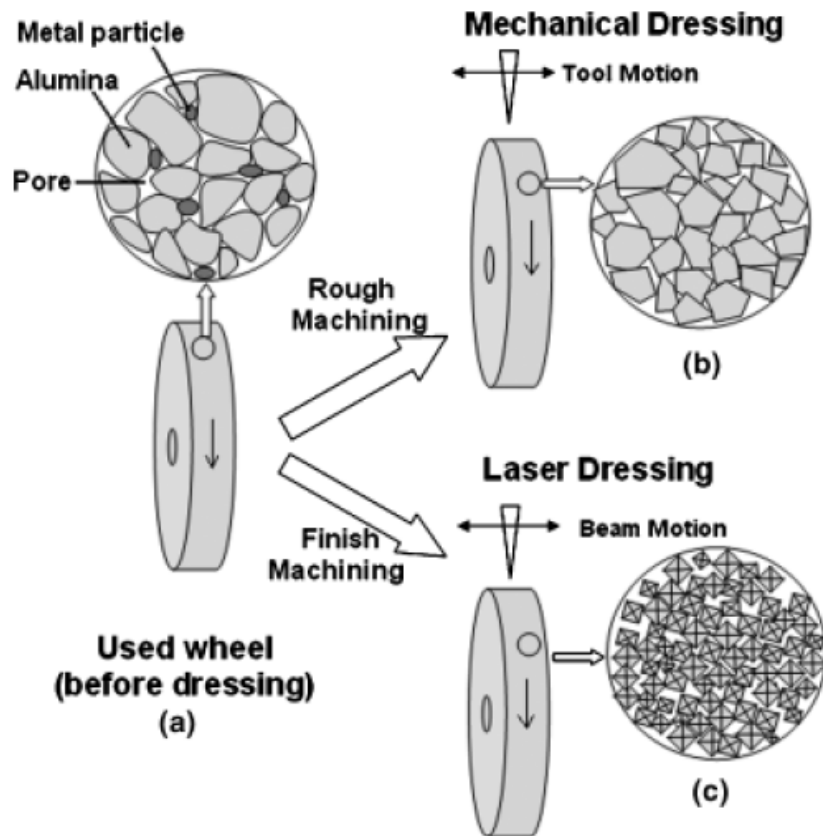


*resulting grain size after laser dressing*

Harimkar, Dahotre:*Int. J. Appl. Ceram. Technol.*, 3, 2006

- new regular build vertices and edge
- production of micro cutting edges
- grain size is well controllable

# Conclusion



- dressing improves surface of tools
- mechanical dressing
  - rough surface
- laser-assisted dressing
  - weakening of surface
  - smaller forces during processing
- laser dressing
  - cracking and melting of grains
  - re-solidification of grains
  - improvement of surface quality

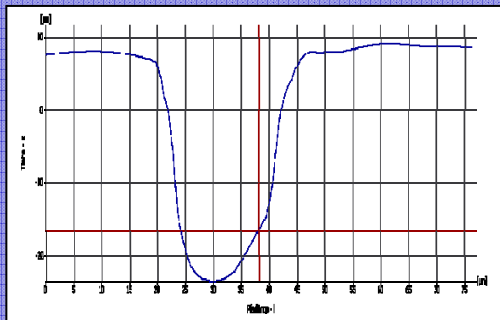
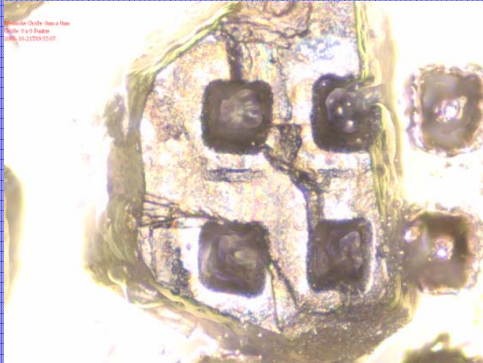
# Our approach

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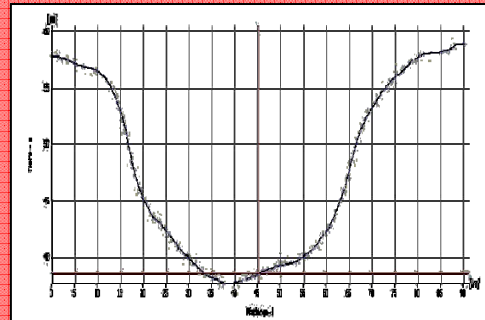
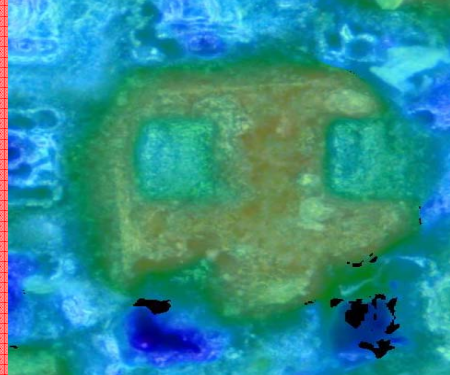
- laser dressing of diamond tools
  - diamond is the hardest material
- diamond – diamond machining is time consuming
- short pulsed laser ns, ps
  - well controlled ablation, small HAZ
- processing tools with complex geometries
  - beam delivery

# Laser ablation on single diamond grain

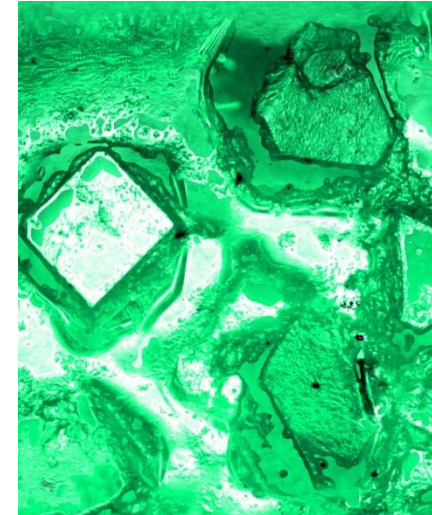
nano - seconds



pico - seconds



replica technique



- structuring is possible with nano- and picosecond pulses
- ➔ • height profiles
- replica technique, pre – post processing comparison

# Outlook

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- detailed analysis from nano- and picosecond ablation experiments
- determination of ablation rate
- microstructure analysis
  - SEM, Raman
- grinding experiments with processed grains, tools
- integration in process, machine design
- CTI - project